**HexBond™ ST1150**  
**Foaming Adhesive Film**  

**Description**  
Foaming core splice adhesive. It is especially useful in bonding sections and edge filling honeycomb. It is ideal for use in thick sections of honeycomb.  

Packaging: Length/width of sections: 305mm x 610mm

**Features**  
- Cure from 120°C/248°F to 180°C/356°F  
- Low volatiles content: ≤ 1% (after cure 1h at 178°C/325°F - 3°C/min)  
- Shelf-life: 1 year at temperature ≤ -18°C/0°F + 15 days at room temperature (≤ 23°C/73°F)

**Applications**  
- Core splice bonding  
- Sandwich construction

**Uncured Adhesive Properties**

<table>
<thead>
<tr>
<th>Form</th>
<th>Weight (g/m²)</th>
<th>Thickness (mm)</th>
<th>Color</th>
<th>Package</th>
</tr>
</thead>
<tbody>
<tr>
<td>ST1150 25 MIL</td>
<td>750 (± 100)</td>
<td>0.64</td>
<td>Blue</td>
<td>Box of 3.72m² (20 sheets)</td>
</tr>
<tr>
<td>ST1150 50 MIL</td>
<td>1500 (± 150)</td>
<td>1.27</td>
<td>Blue</td>
<td>Box of 3.72m² (20 sheets)</td>
</tr>
</tbody>
</table>

**Instructions For Use**  
Refer to the Safety Data Sheet before handling.  

- To avoid any moisture, allow the adhesive to warm at room temperature before opening the waterproof polyethylene bag  
- Bonding surfaces should be clean, dry and properly prepared  
- Remove protective papers before bonding  
- Typical cure cycles: 1h at 120°C/248°F at 175°C/347°F  
  Heat-up 248°F to 4°C/min
### Mechanical Properties

<table>
<thead>
<tr>
<th>Test</th>
<th>Test Temperature (°C / °F)</th>
<th>Curing 1h 120°C / 248°F (3°C/min)</th>
<th>Curing 1h 175°C / 347°F (3°C/min)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Expansion (1) (%)</td>
<td>23°C</td>
<td>120</td>
<td>170</td>
</tr>
<tr>
<td>Flow on vertical wall (2) (mm)</td>
<td>23°C</td>
<td>-</td>
<td>0.2</td>
</tr>
<tr>
<td>Tube shear strength (3) (MPa / psi)</td>
<td>-55 / -67</td>
<td>10 / 1450</td>
<td>10 / 1450</td>
</tr>
<tr>
<td></td>
<td>23 / 73</td>
<td>8.0 / 1160</td>
<td>8.5 / 1230</td>
</tr>
<tr>
<td></td>
<td>80 / 176</td>
<td>7.5 / 1090</td>
<td>8.0 / 1160</td>
</tr>
<tr>
<td></td>
<td>23 / 73 WA (4)</td>
<td>7.5 / 1090</td>
<td>8.0 / 1160</td>
</tr>
</tbody>
</table>

(1) According to EN 2667-3  
(2) According to EN 2667-4  
(3) According to EN2267-2, on aluminum 5052 treated with sulfo-chromic acid etch  
(4) Wet ageing: 70°C, 85% relative humidity, saturation

This information is provided for informal purposes only, without legal responsibility and does not constitute a specification. Users are expected to perform adequate verification and testing to ensure that materials meet required specification.

---

**For more information**

Hexcel is a leading worldwide supplier of composite materials to aerospace and industrial markets. Our comprehensive range includes:

- HexTow® carbon fibers
- HexForce® reinforcements
- HiMax™ multiaxial reinforcements
- HexPly® prepregs
- HexAM™ additive manufacturing
- HexMC® molding compounds
- HexFlow® RTM resins
- Redux® adhesives
- HexTool® tooling materials
- HexWeb® honeycombs
- Acousti-Cap® sound attenuating honeycomb
- Engineered core
- Engineered products
- Polyspeed™ laminates

For US quotes, orders and product information call toll-free 1-800-688-7734. For other worldwide sales office telephone numbers and a full address list, please go to:

http://www.hexcel.com/contact/salesoffice

©2018 Hexcel Corporation – All rights reserved. Hexcel Corporation and its subsidiaries ("Hexcel") believe that the technical data and other information provided herein was materially accurate as of the date this document was issued. Hexcel reserves the right to update, revise or modify such technical data and information at any time. Any performance values provided are considered representative but do not and should not constitute a substitute for your own testing of the suitability of our products for your particular purpose. Hexcel makes no warranty or representation, express or implied, including but not limited to the implied warranties of merchantability and fitness for a particular purpose, and disclaims any liability arising out of or related to, the use of or reliance upon any of the technical data or information contained in this document.